

LED LAMPS SPECIFICATION

TOTAL PAGE: 5 PAGE: 1

REVISION: 1.0

• COMMODITY : 1.0"Lead Tower 2.0 ϕ

● DEVICE NUMBER: BL-S4136

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2003.03.31	1.0	1.0	1.0	1.0	1.0			Original Released

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LED LAMPS SPECIFICATION

•COMMODITY : 1.0"Lead Tower 2.0 ϕ PAGE: 2 •DEVICE NUMBER : BL-S4136 VERSION : 1.0

●ELECTRICAL AND OPTICAL CHARACTERISTICS (Ta=25°C)

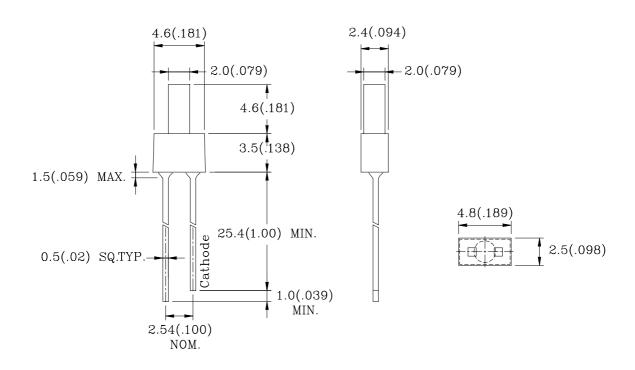
Chip			Absolute Maximum				Electro-optical			Viewing
	Peak	Lens		Rat	ting		D	ata (At 2	20mA)	Angle
Emitted	Wave		Δλ	Pd	If	Peak	Vf	(V)	Iv Typ.	$2\theta 1/2$
Color	Length $\lambda P(nm)$	Appearance	(nm)	(mW)	(mA)	If(mA)	Тур.	Max.	(mcd)	(deg)
Orange	635	Orange Diffused	45	80	30	150	2.0	2.6	7.0	70

Remark: Viewing angle is the Off-axis angle at which the luminous intensity is half the axial luminous intensity.

●ABSOLUTE MAXIMUM RATINGS (Ta=25°C)

Reverse Voltage	5V
Reverse Current (V_R =5V)	
Operating Temperature Range	
Storage Temperature Range	
Lead Soldering Temperature	260°C For 5 Seconds

•PACKAGE DIMENSIONS



NOTES: 1.All dimensions are in millimeters (inches).

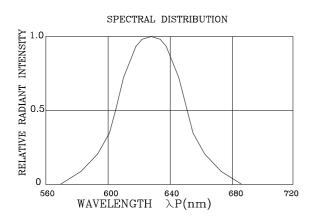
- 2. Tolerance is \pm 0.25mm (0.01") unless otherwise specified.
- 3.Lead spacing is measured where the leads emerge from the package.
- 4. Specifications are subject to change without notice.

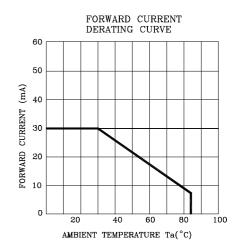
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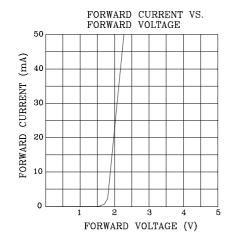
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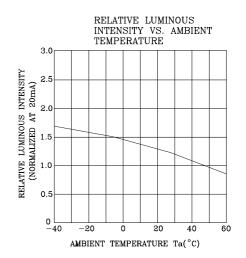


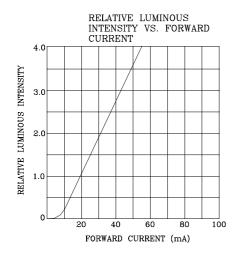


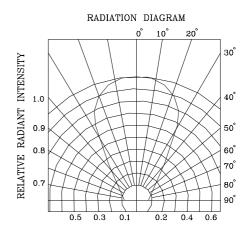
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LED LAMPS SPECICATION RELIABILITY TEST

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Classification	Test Item	Reference Standard	Test Conditions	Result
Endurance Test	Operation Life	MIL-STD-750:1026 MIL-STD-883:1005 JIS C 7021 :B-1	Connect with a power If=20mA Ta=Under room temperature Test time=1,000hrs	0/100
	High Temperature High Humidity Storage	MIL-STD-202:103B JIS C 7021 :B-11	Ta= 85° C $\pm 5^{\circ}$ C RH= 90% - 95% Test time= 240 hrs	0/100
	High Temperature Storage	MIL-STD-883:1008 JIS C 7021 :B-10	High Ta=105°C ±5°C Test time=1,000hrs	0/100
	Low Temperature Storage	JIS-C-7021 :B-12	Low Ta=-55°C ±5°C Test time=1,000hrs	0/100
Environmental Text	Temperature Cycling	MIL-STD-202:107D MIL-STD-750:1051 MIL-STD-883:1010 JIS C 7021 :A-4	-55°C ~25°C ~105°C ~25°C 30min 5min 30min 5min Test Time=10cycle	0/100
	Thermal Shock	MIL-STD-202:107D MIL-STD-750:1051 MIL-STD-883:1011	-55 °C ± 5 °C ~ 105 °C ± 5 °C 10min 10min Test Time=10cycle	0/100
	Solder Resistance	MIL-STD-202:201A MIL-STD-750:2031 JIS C 7021 :A-1	T.sol= 260 ± 5 °C Dwell Time= 5 ± 1 sec.	0/50
	Solder ability	MIL-STD-202:208D MIL-STD-750:2026 MIL-STD-883:2003 JIS C 7021 :A-2	T.sol=230 ± 5 °C Dwell Time=5 ± 1 sec.	0/50
	Lead Bending Stress	MIL-STD-750:2036 JIS C 7021 :A-11	0 °~90 °~0 ° bend, 3 cycles Weight 250g	0/50

JUDGMENT CRITERIA OF FAILURE FOR THE RELIABILITY

Measuring items	Symbol	Measuring conditions	Judgement criteria for failure
Forward voltage	$ m V_{F}$	If=20mA	Over Ux1.2
Reverse current	Ir	Vr=5V	Over Ux2
Luminous intensity	Iv	If=20mA	Below Sx0.5

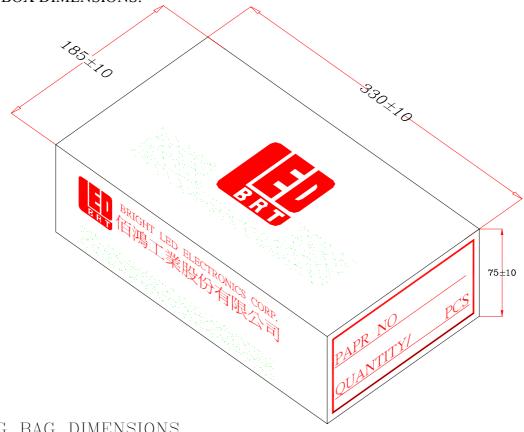
Notes: 1.U means the upper limit of specified characteristics. S means initial value.

2.Measurment shall be taken between 2 hours and after the test pieces have been returned to normal ambient conditions after completion of each test.

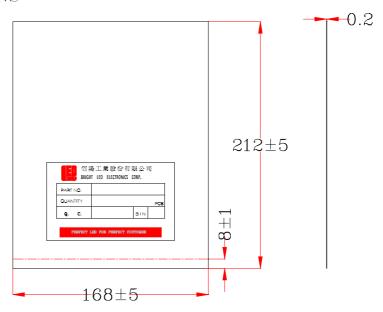
PACKAGING DIMMENSIONS

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PACKAGING BOX DIMENSIONS:



PACKAGING BAG DIMENSIONS



NOTES:

- 1.500 PCS PER BAG, 5K PCS PER B0X
- 2.ALL Dimensions are in millimeters (inches).
- 3. Specifications are subject to change without notice.